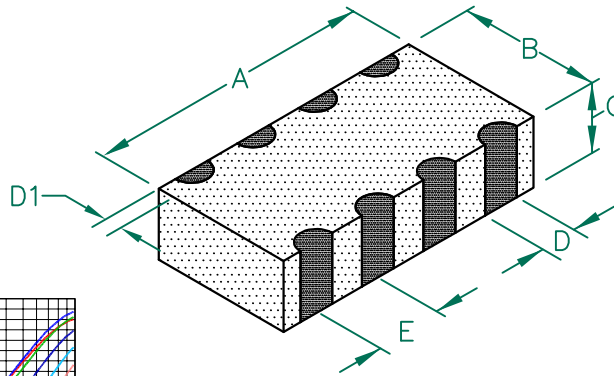


PHYSICAL DIMENSIONS:

A	3.20 [.126]	± 0.20 [.008]
B	1.60 [.063]	± 0.20 [.008]
C	0.80 [.031]	± 0.20 [.008]
D	0.40 [.016]	± 0.15 [.006]
D1	0.30 [.012]	± 0.200 [.008]
E	0.80 [.031]	± 0.10 [.004]

DA1206D600R-10

**UNCONTROLLED
DOCUMENT**



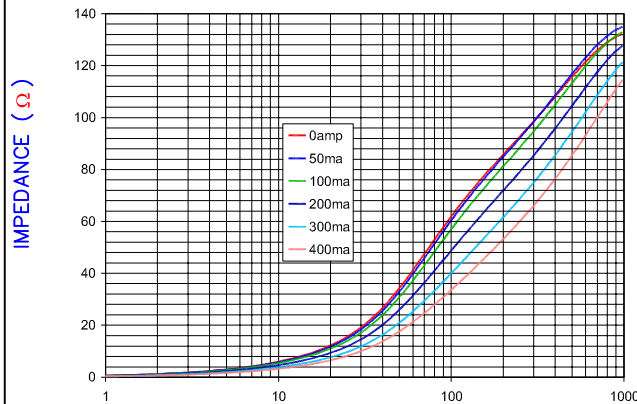
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	60	
Minimum	45	
Maximum	75	0.2
400 mA		
LINE TO LINE INSULATION RESISTANCE >100 M Ω AT 75 VOLTS.		

NOTES: UNLESS OTHERWISE SPECIFIED

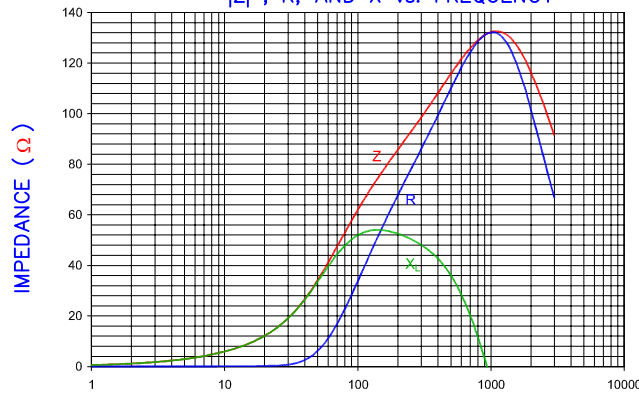
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMPERATURE TEMP: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (INCLUDING SELF-HEATING)

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



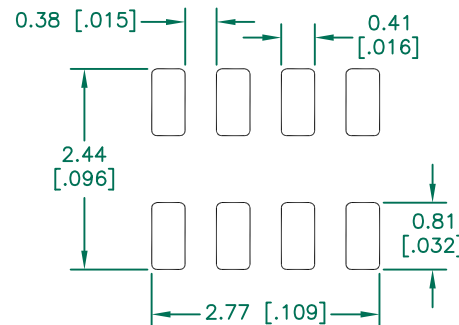
FREQUENCY (MHz)

|Z|, R, AND X vs. FREQUENCY



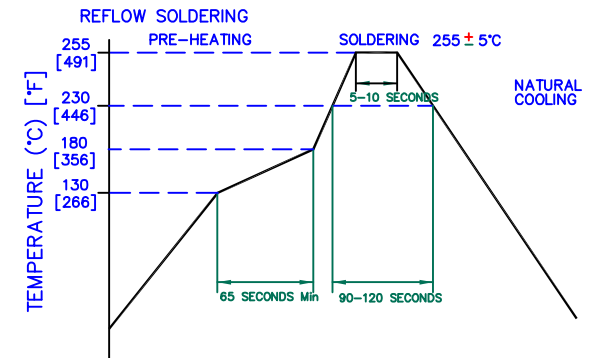
FREQUENCY (MHz)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762
(0.030) to this dimension)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
E	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU				
D	UPDATE COMPANY LOGO	05/22/09	JRK				
C	D1 dim chgd from 0.008 $\pm$ 0.004 to 0.012 $\pm$ 0.008. UPDATE COMPANY LOGO	10/31/07	JRK				
B	ADD ROHS COMPLIANT SYMBOL	08/20/04	TMB				
A	ORIGINAL DRAFT	04/02/04	TMB				
REV	DESCRIPTION	DATE	INT	PROJECT/PART NUMBER: DA1206D600R-10 DATE: 04/02/04 SCALE: NTS SHEET: 2 of 2			